PEREGRINE MATERIAL DECLARATION FORM

Product:	**PE43704**
Ordering Codes:	**PE43704B-Z**
Description:	**UltraCMOS® RF Digital Step Attenuator, 7-bit, 31.75 dB with Optional VssEXT Bypass Mode 9 kHz - 8 GHz**
Package:	**32L 5x5 QFN**
Environmental Compliance:	EU **RoHS2** Directive 2011/65/EC, **REACH** - EU ECHA SVHC, **Arsenic Free**, **JIG 101** - EIA/EICTA/JEITA, **Halogen Free** - IEC61249-2-21, **PFOS Free** - 2006/122/EC, **Antimony Trioxide Free**
Lead Finish:	**NiPdAu**
Availability:	**Now**

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	3.492261	5.29%	52,863.65
Die	Aluminum	7429-90-5	0.010623	0.02%	160.80
Die	Silicon	7440-21-3	0.000708	0.00%	10.72
Die	Arsenic	7440-38-2	0.000004	0.00%	0.05
Die	Boron	7440-42-8	0.000004	0.00%	0.05
Die	Phosphorus	7723-14-0	0.000014	0.00%	0.21
Die	Titanium	7440-32-6	0.001770	0.00%	26.80
Die	Tungsten	7440-33-7	0.035409	0.05%	536.00
Die	Cobalt	7440-48-4	0.000071	0.00%	1.07
Die	Copper	7440-50-8	0.000028	0.00%	0.43
Leadframe	Copper	7440-50-8	26.714000	40.44%	404,379.65
Leadframe	Iron	7439-89-6	0.643900	0.97%	9,746.95
Leadframe	Zinc	7440-66-6	0.032900	0.05%	498.02
Leadframe	Phosphorous	7723-14-0	0.008200	0.01%	124.13
Die Attach	Silver	7440-22-4	0.287200	0.43%	4,347.45
Die Attach	Epoxy Resin	9003-36-5	0.035900	0.05%	543.43
Die Attach	Diluent	26447-14-3	0.021500	0.03%	325.45
Die Attach	Dicyandiamide	461-58-5	0.003600	0.01%	54.49
Die Attach	Hardener	620-92-8	0.010800	0.02%	163.48
Wire	Gold	7440-57-5	0.552900	0.84%	8,369.45
Plating	Others	Proprietary	0.000100	0.00%	1.51
Plating	Nickel	7440-02-0	0.180330	0.27%	2,729.72
Plating	Palladium	7440-05-3	0.014580	0.02%	220.70
Plating	Gold	7440-57-5	0.000580	0.00%	8.78
Molding Compound	Silica Fused	60676-86-0	31.191100	47.22%	472,151.16
Molding Compound	Epoxy Resin	Trade secret	1.360600	2.06%	20,595.90
Molding Compound	Phenol Resin	Trade secret	1.360600	2.06%	20,595.90
Molding Compound	Carbon Black	1333-86-4	0.102000	0.15%	1,544.01
Total Weight (mg)			**66.061682**	100.00%	1,000,000